ABSTRACT

APPARATUS FOR TREATING SUBSTRATES USING PLASMA, METHOD FOR SUPPLYING PLASMA AND METHOD FOR TREATING SUBSTRATES USING PLASMA

After oxygen plasma is supplied onto a substrate to primarily strip photoresist formed on the substrate, the oxygen plasma and fluorine-based plasma are supplied to secondly strip the photoresist and residues. The oxygen plasma is directly discharged using a discharger, while the fluorine-based plasma is indirectly generated by the oxygen plasma by supplying a fluorine-based source gas onto the flow path of the oxygen plasma. The plasma is supplied via a baffle where a plurality of through-holes are formed, and ions contained in the plasma are filtered by the grounded baffle. (Fig. 1)